

FIG. 1
Typical LSSD Configuration

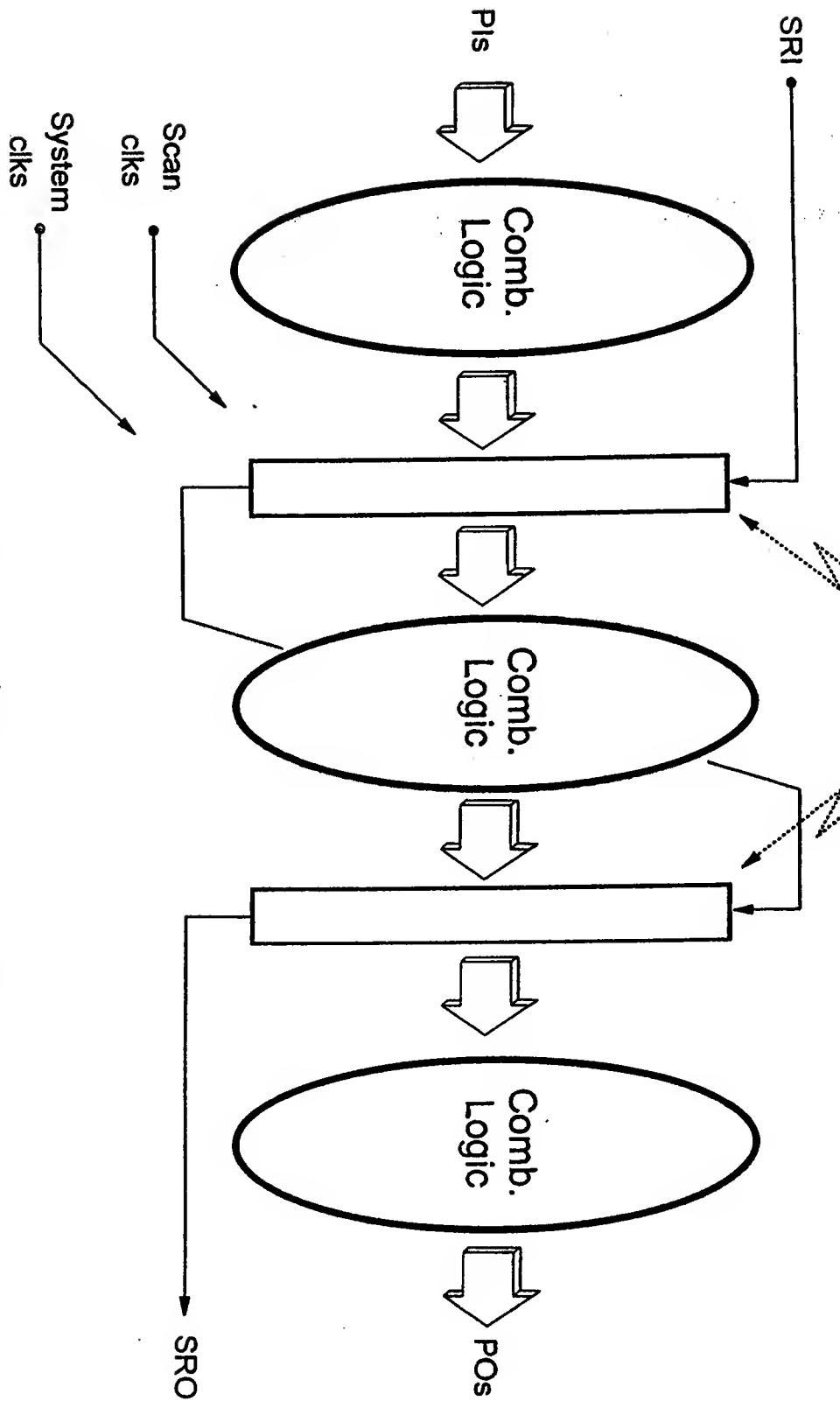
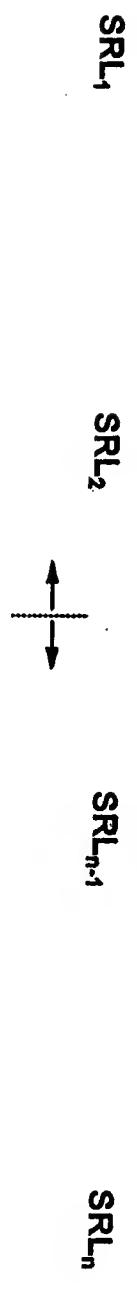
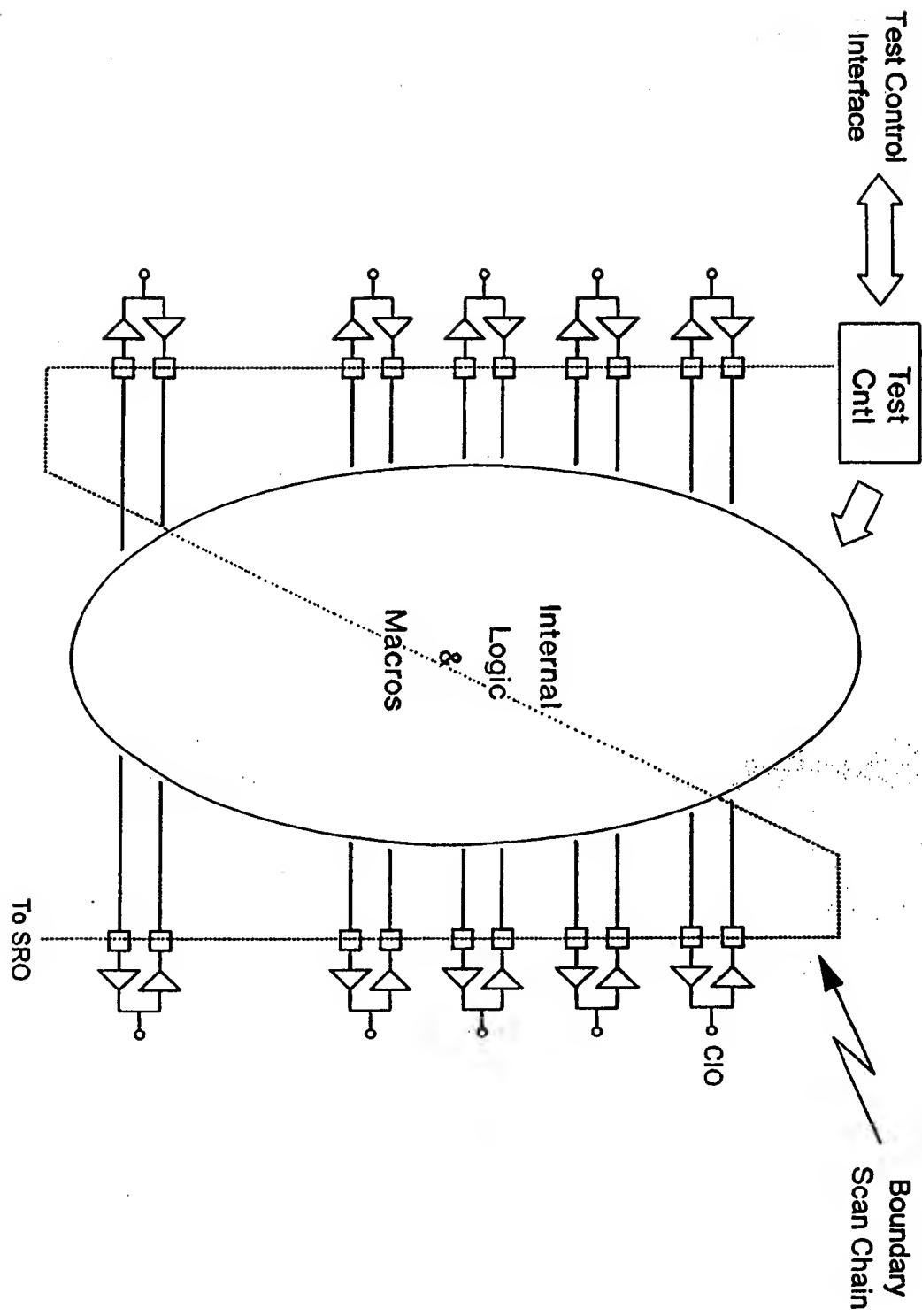


FIG. 2



Typical LSSD Scan Chain

FIG. 3 Boundary Scan Configuration



Typical Common I/O Configuration
FIG. 4

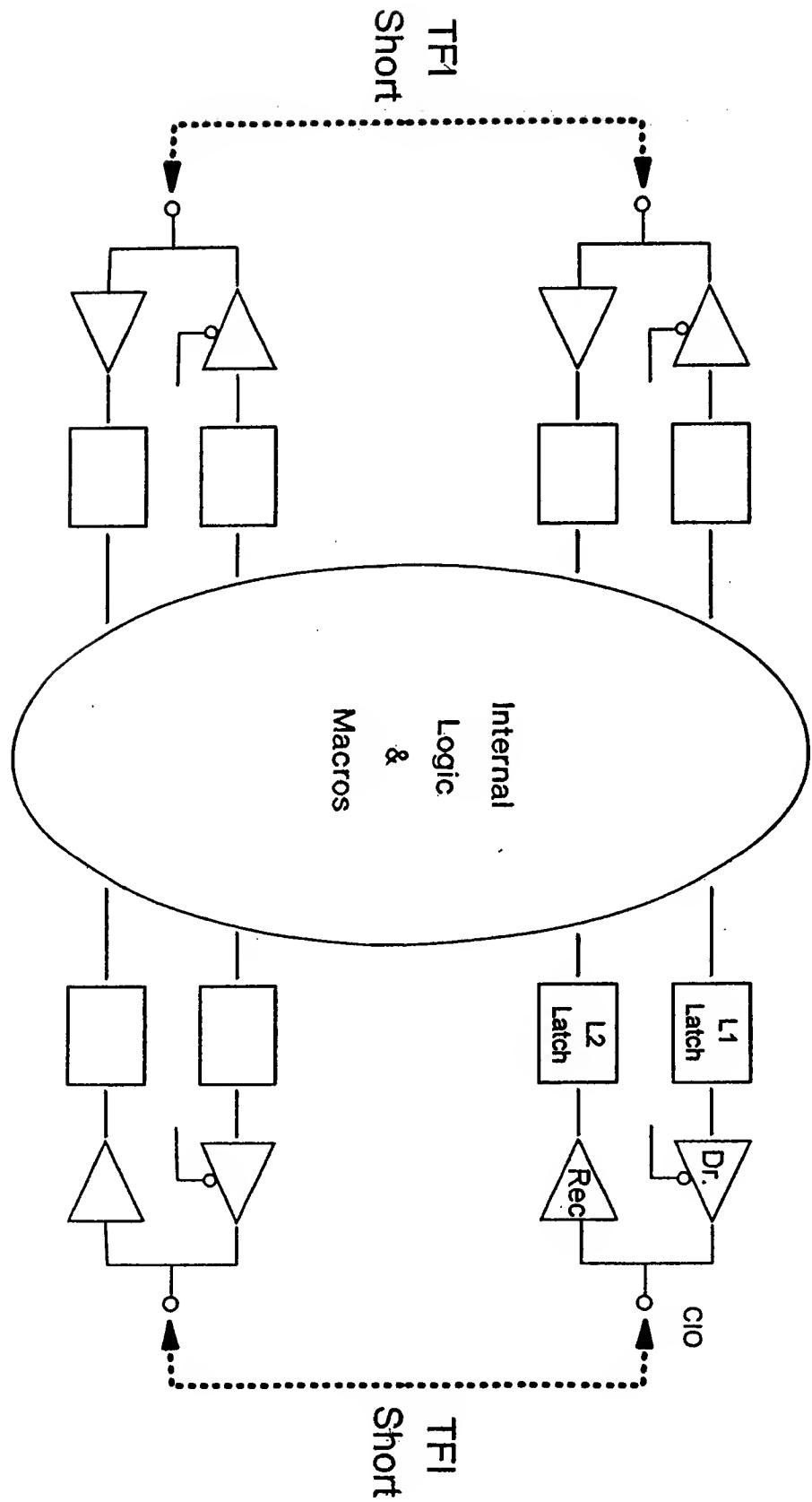


FIG. 5A
Standard

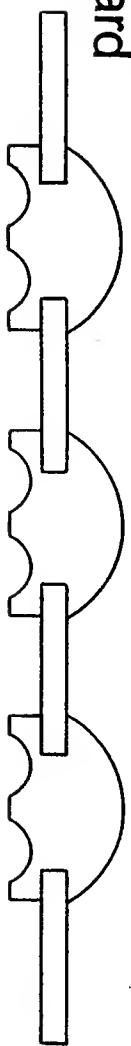


FIG. 5B

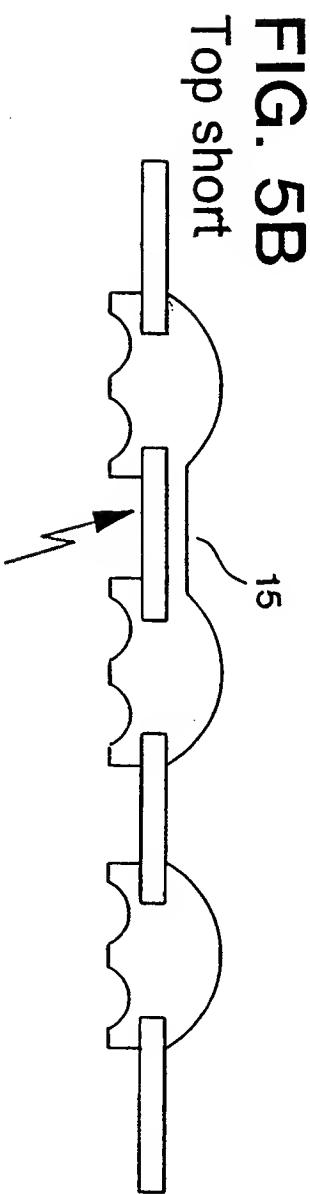


FIG. 5C

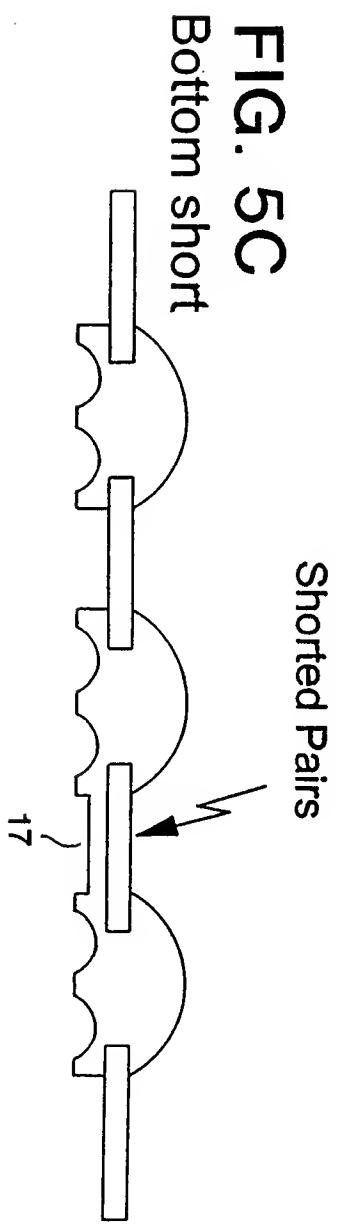


FIG. 5D
Starting Material

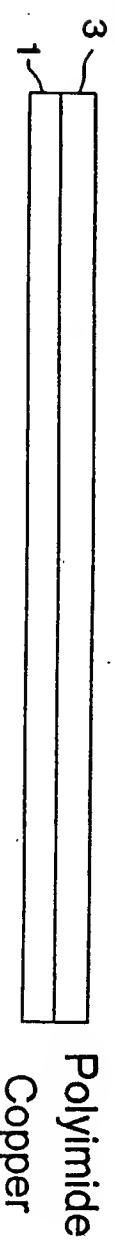


FIG. 6A
Laser Ablate
Blind Vias

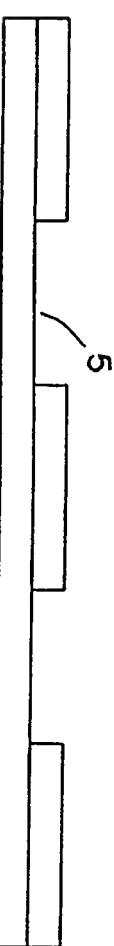


FIG. 6B
Electroplate Copper
in Vias

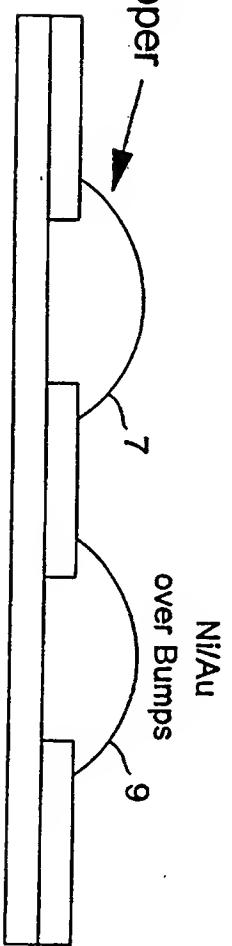
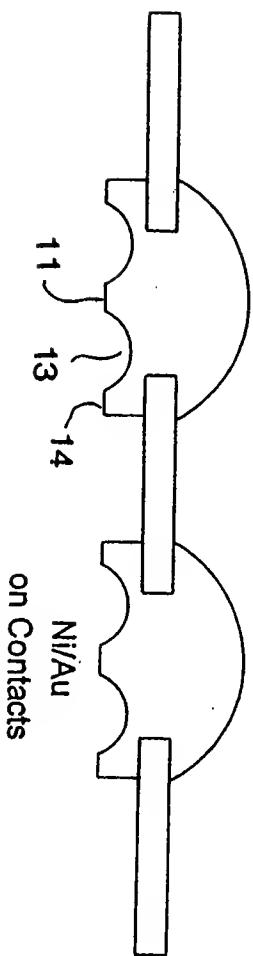


FIG. 6C
Etch Pads
in Copper



Standard TFI Probe Build Process

FIG. 7A
Typical TFI
Probe

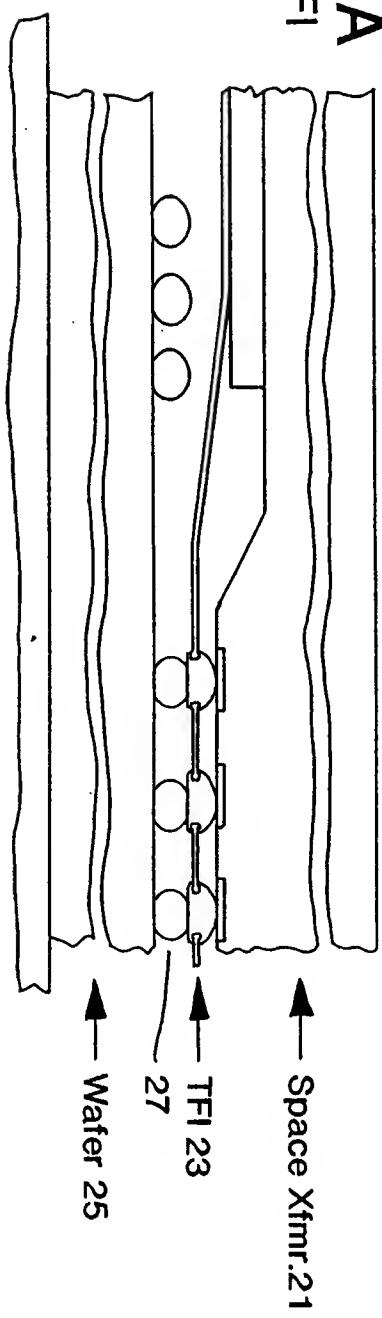


FIG. 7B
TFI Probe with
Shorted Pair

